

SLU SERIES

8 to 15kV, 450 to 850mA, 40 to 50nS Surface Mount Diodes

Features

- Long Surface Mount Package
- J Lead or Gullwing Package Option
- Available in Cut Tape and 1000 Piece Reels
- Molded Plastic Body, ANSI/UL94 V-0 Rated Material

Specifications¹

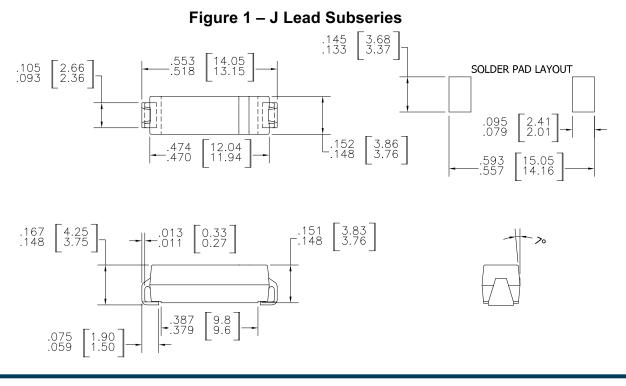
Part Number	V _{RRM} V	I _{FAVM1} 2 mA	I _{FAVM2} 2 mA	I _{FAVM3} 2 mA	V _F V	Ι _R μΑ	I _{FSM} А	С _Ј pF	T _{RR} ² nS	R _{θJL} °C/W	R _{θJC} °C/W
J Lead Subseries (Figure 1)											
SLU08M	8000	850	450	400	12	0.5	20	7.5	40	13	20
SLU15M	15000	450	250	240	16	0.5	20	3.5	50	13	20
Gullwing Subseries (Figure 2)											
SLU08MG	8000	850	450	400	12	0.5	20	7.5	40	13	20
SLU15MG	15000	450	250	240	16	0.5	20	3.5	50	13	20

Temperature °C						
Operating Temperature	-55 to 150					
Storage Temperature	-55 to 175					
Maximum Junction Temperature	150					

¹25°C ambient temperature unless stated otherwise. ²Check Specification Definitions for conditions details.

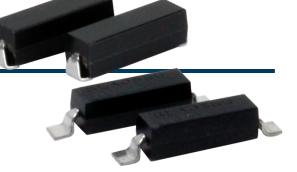
Drawings

Dimensions in inches [mm], tolerances ± 0.020 except as noted



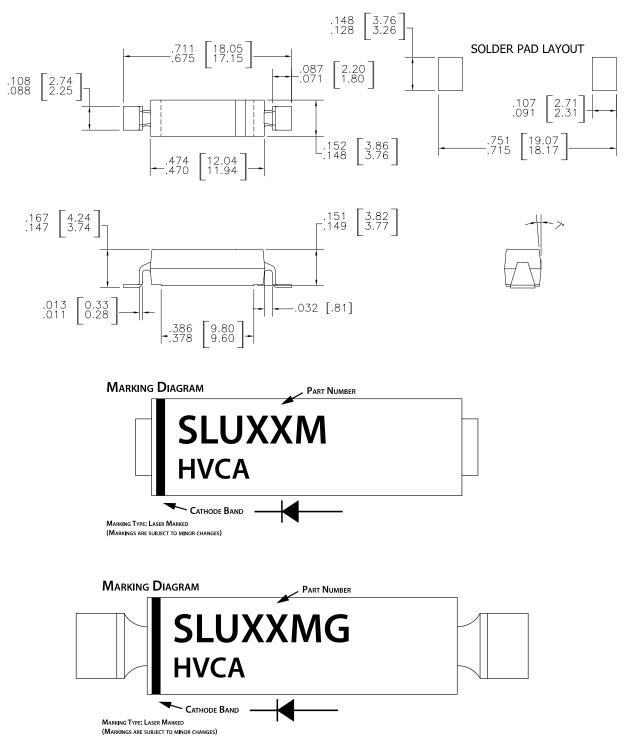


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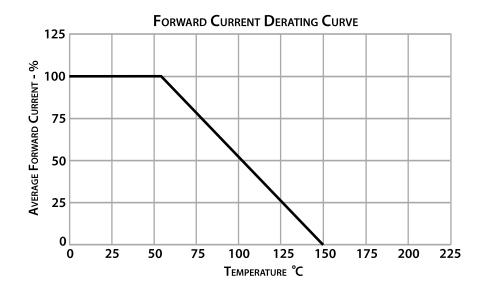




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Specification Definitions

	Specifications	Conditions
V _{RRM}	Maximum Repetitive Reverse Voltage	-
IFAVM1	Maximum Average Forward Current	At $T_L = 55^{\circ}C$
I _{FAVM2}	Maximum Average Forward Current	At $T_L = 100^{\circ}C$
I FAVM3	Maximum Average Forward Current	At $T_c = 80^{\circ}C$
VF	Maximum Forward Voltage Drop	At 100mA
I _R	Maximum Leakage Current	At V _{RRM}
I _{FSM}	Maximum Surge Current	At 8.3 mS, Single Half Sine
CJ	Typical Junction Capacitance	At V_R = 0VDC, f = 1MHz
T _{RR}	Maximum Reverse Recovery Time	I_F = 250mA; I_R = -500mA; I_{RR} = -125mA (<i>SLU08M</i> , <i>SLU08MG</i>) I_F = 100mA; I_R = -200mA; I_{RR} = -50mA (<i>SLU15M</i> , <i>SLU15MG</i>)
R _{θJL}	Typical Thermal Resistance Junction to Lead	Device Mounted on 0.2" x 0.2" (5mm x 5mm) Copper Solder Pads
R _{θJC}	Typical Thermal Resistance Junction to Case	Device Mounted on 0.2" x 0.2" (5mm x 5mm) Copper Solder Pads

Note: Specifications subject to change without notice. Photo is representation only.



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